



# P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
	0.060 at V <sub>GS</sub> = - 4.5 V	- 4.7				
- 20	0.084 at V <sub>GS</sub> = - 2.7 V	- 3.9	7.53 nC			
	0.100 at V <sub>GS</sub> = - 2.5 V	- 3.4				

#### **FEATURES**

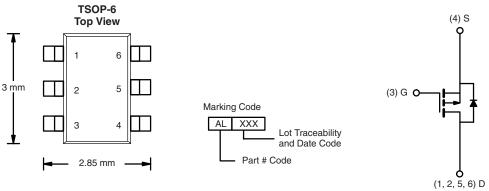
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- **PWM Optimized**
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- HDD
- Asynchronous Rectification
- Load Switch for Portable Devices



Ordering Information: Si3443CDV-T1-E3 (Lead (Pb)-free)

Si3443CDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

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Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	- 20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 12	· ·	
	T <sub>C</sub> = 25 °C		- 5.97		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I_	- 4.6		
Continuous Brain Current (1) = 150 O)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	- 4.7 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		- 3.4 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	- 20		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		- 2.67		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 1.71 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		3.2		
Marian and David Dispiration	T <sub>C</sub> = 70 °C		2.05		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C		1.28 <sup>b, c</sup>		
Operating Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	51	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	32	39	O/ VV		

#### Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 110 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V
$V_{DS}$ Temperature Coefficient $\Delta V_{DS}/T_{J}$		I <sub>D</sub> = - 250 μA		- 18.8		\//06
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η ΙΔ = - 250 μΑ		3.25		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	- 0.6		- 1.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
Zarra Cata Valta va Duaira Comunant		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.7 A		0.0500	0.0600	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.7 V, I <sub>D</sub> = - 3.9 A		0.0692	0.0840	Ω
		V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 3.4 A		0.0830	0.1000	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 4.7 A		15		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			610		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		132		
Reverse Transfer Capacitance	C <sub>rss</sub>			105		
Total Cata Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -4.7 \text{ A}$		8.26	12.4	nC
Total Gate Charge	$Q_g$			7.53	11.3	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.7 \text{ A}$		1.53		
Gate-Drain Charge	$Q_{gd}$			2.37		
Gate Resistance	$R_{g}$	f = 1 MHz	1.7	8.5	12.75	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			27	41	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_L = 2.12 \Omega$		59	88.5	
Turn-Off Delay Time t <sub>d(c</sub>		$I_D \cong$ - 4.7 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		30	45	ns
Fall Time	t <sub>f</sub>			11	16.5	
<b>Drain-Source Body Diode Characteristic</b>	s					
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 2.67	А
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 20	^
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 1.7 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time t <sub>rr</sub>				20	30	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 1.7.4 dl/dt = 100.4/10. T = 05.90		9	13.5	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -1.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		15		ns
Reverse Recovery Rise Time	t <sub>b</sub>			5.1		

### Notes:

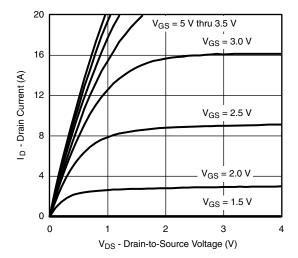
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

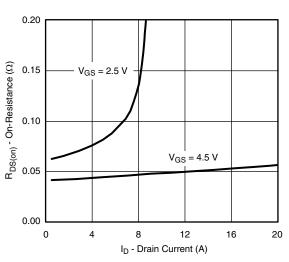
b. Guaranteed by design, not subject to production testing.



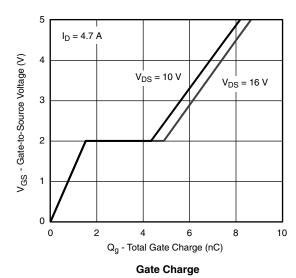
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

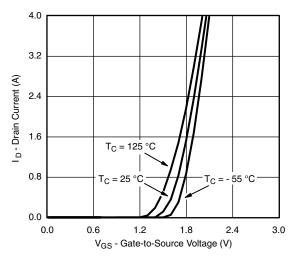


#### **Output Characteristics**

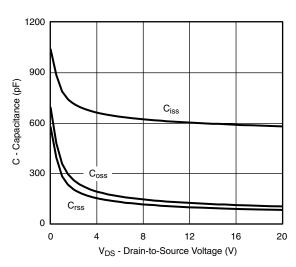


## On-Resistance vs. Drain Current and Gate Voltage

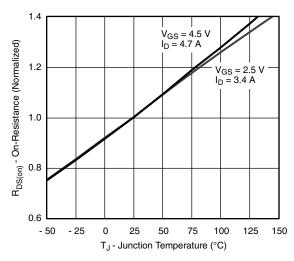




#### **Transfer Characteristics**



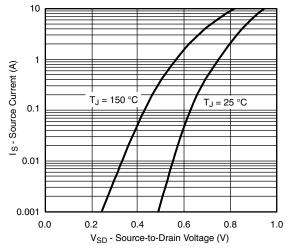
## Capacitance

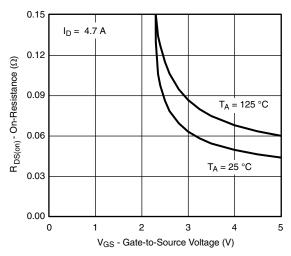


On-Resistance vs. Junction Temperature

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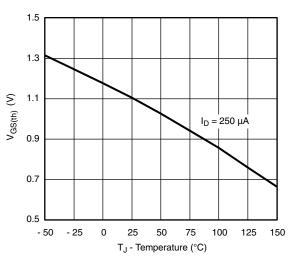
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

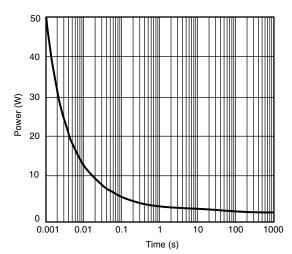




#### Source-Drain Diode Forward Voltage

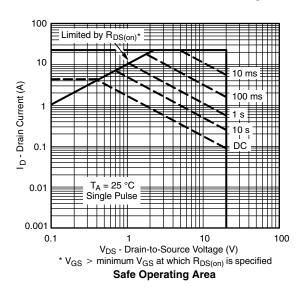






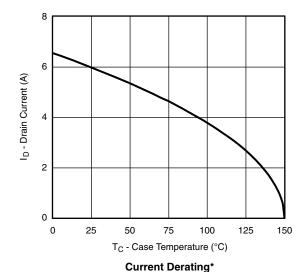
#### Threshold Voltage

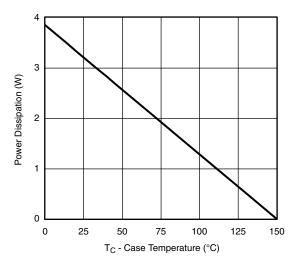
Single Pulse Power, Junction-to-Ambient





## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



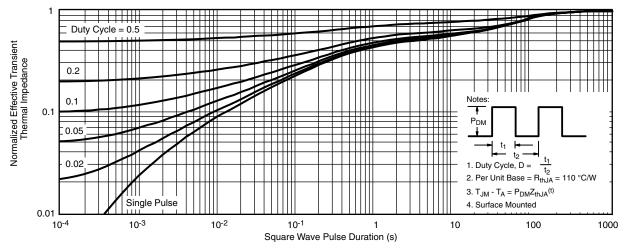


Power, Junction-to-Foot

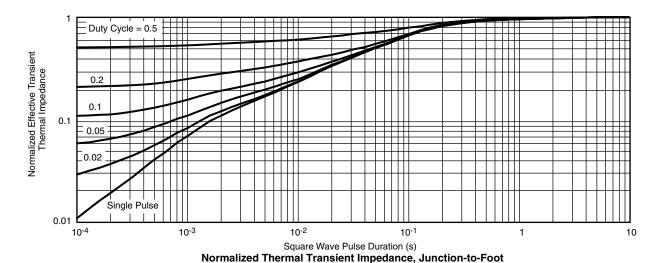
 $<sup>^*</sup>$  The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150  $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



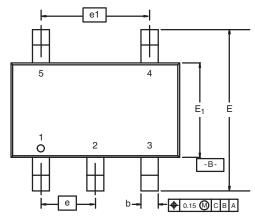
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?74495.

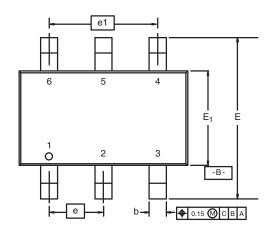




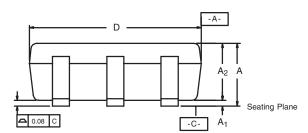
TSOP: 5/6-LEAD

**JEDEC Part Number: MO-193C** 

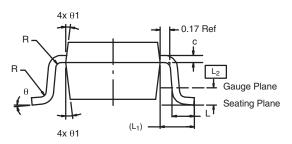




**5-LEAD TSOP** 





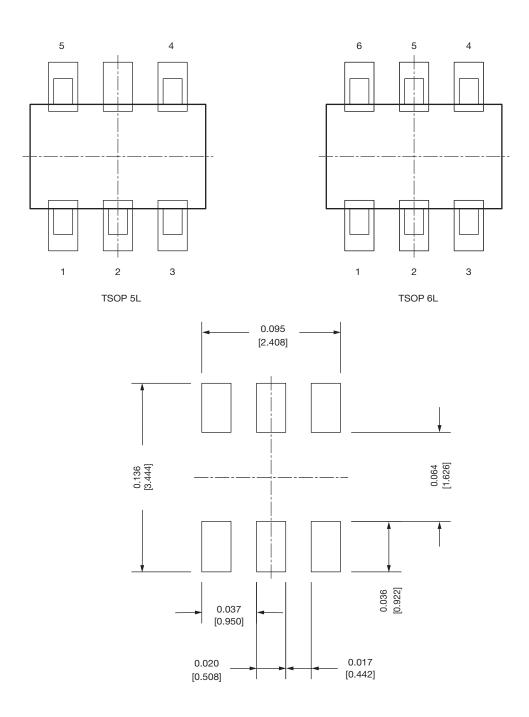


	MIL	LIMETER	RS	INCHES				
Dim	Min	Nom	Max	Min	Nom	Max		
Α	0.91	-	1.10	0.036	-	0.043		
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004		
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039		
b	0.30	0.32	0.45	0.012	0.013	0.018		
С	0.10	0.15	0.20	0.004	0.006	0.008		
D	2.95	3.05	3.10	0.116	0.120	0.122		
E	2.70	2.85	2.98	0.106	0.112	0.117		
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067		
е		0.95 BSC		0.0374 BSC				
e <sub>1</sub>	1.80	1.90	2.00	0.071	0.075	0.079		
L	0.32	-	0.50	0.012	-	0.020		
L <sub>1</sub>		0.024 Ref						
L <sub>2</sub>		0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-		
θ	0°	4°	8°	0°	4°	8°		
θ1	7° Nom 7° Nom							
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540								

Document Number: 71200 18-Dec-06



# Recommended Land Pattern For TSOP-5L / TSOP-6L



### Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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